

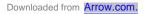
Film Capacitors

EMI Suppression Capacitors (MKP)

 Series/Type:
 B32021 ... B32026

 Date:
 June 2020

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EMI suppression capacitors (MKP)

Y2 / 300 V AC

B32021 ... B32026

Typical applications

- Y2 class for interference suppression
- "Line to ground" applications.

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1:2013): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Very small dimensions
- Good self-healing properties
- High voltage capability
- RoHS-compatible
- Halogen-free capacitors available on request

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

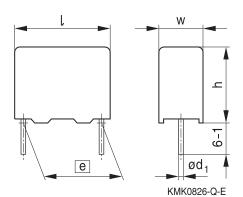
Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (Y2), dielectric code (MKP), climatic category, passive flammability category, approvals.

Delivery mode

Bulk (untaped) Taped (Ammo pack or reel) For taping details, refer to chapter "Taping and packing"

Dimensional drawing



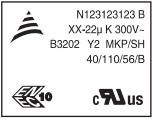
Dimensions in mm

Lead spacing e ±0.4	Lead diameter d ₁ ±0.05	Туре
10	0.6	B32021
15 27.5	0.8	B32022 B32024
37.5	1.0	B32026



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Marking example (position of marks may vary):



KMK1547-B

Approvals

Approval marks	Standards	Certificate
/]//	EN 60384-14:2014/A1:2016	40018909
	IEC 60384-14:2013/AMD1:2016	
	UL 1414:2000	E97863 / E157153
<i>F1</i>	UL 1283:2005	
	CSA C22.2 No.1:2004	E97863 / E157153 (approved by UL)
c 91	CSA C22.2 No.8:2013	
	UL 60384-14:2014	E97863 (approved by UL)
c 91 us	CSA E60384-14:2013	

Notes:	Effective January 2014, only for EMI supression capacitors:
	 UL 60384-14:2014 certification replaces both UL 1414:2000 and UL 1283:2005 standards.
	 CSA C22.2 No.1.2004 and CSA C22.2 No.8:2013 are replaced by CSA E60384-14:2013.
	 References like 1414, 1283 are removed from the capacitor marking.
	Capacitors under UL 1414:2000, UL 1283:2005 produced during or before 2013, are accepted under UL scope.
	Capacitors under CSA C22.2 No.1:2004 / CSA C22.2 No.8:2013 produced during or before 2013, are accepted under cUL scope.



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Overview of available types

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
Туре	B32021	B32022	B32023	B32024	B32026
C _R (μF)					
0.0010					
0.0015					
0.0022					
0.0033					
0.0047					
0.0056					
0.0068					
0.0082					
0.010					
0.015					
0.022					
0.033					
0.047					
0.056					
0.068					
0.082					
0.10					
0.15					
0.22					
0.33					
0.39					
0.47					
0.56					
0.68					
0.82					
1.0					



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Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Ammo	Reel	Untaped
		$w \times h \times l$	(composition see	pack		
mm	μF	mm	below)	pcs./MOQ	pcs./MOQ	pcs./MOQ
10	0.0010	$4.0\times 9.0\times 13.0$	B32021A3102+***	4000	6800	4000
	0.0015	$4.0\times 9.0\times 13.0$	B32021A3152+***	4000	6800	4000
	0.0022	$4.0\times 9.0\times 13.0$	B32021A3222+***	4000	6800	4000
	0.0033	$4.0\times 9.0\times 13.0$	B32021A3332+***	4000	6800	4000
	0.0047	$5.0\times11.0\times13.0$	B32021A3472+***	3320	5200	4000
	0.0056	$5.0\times11.0\times13.0$	B32021A3562+***	3320	5200	4000
	0.0068	$5.0\times11.0\times13.0$	B32021A3682+***	3320	5200	4000
	0.0082	$6.0\times12.0\times13.0$	B32021A3822+***	2720	4400	4000
	0.010	$6.0\times12.0\times13.0$	B32021A3103M***	2720	4400	4000
15	0.010	$5.0\times10.5\times18.0$	B32022A3103+***	4680	5200	4000
	0.015	$6.0\times11.0\times18.0$	B32022A3153+***	3840	4400	4000
	0.022	$6.0\times12.0\times18.0$	B32022A3223M***	3840	4400	4000
	0.022	$7.0\times12.5\times18.0$	B32022B3223+***	3320	3600	4000
	0.033	$8.0\times14.0\times18.0$	B32022A3333+***	2920	3000	2000
	0.047	$8.5 \times 14.5 \times 18.0$	B32022A3473M***	2720	2800	2000
	0.047	9.0 imes 17.5 imes 18.0	B32022B3473+***	2560	2800	2000
	0.056	9.0 imes 17.5 imes 18.0	B32022A3563+***	2560	2800	2000
	0.068	9.0 imes 17.5 imes 18.0	B32022A3683M***	2560	2800	2000
	0.082	$11.0\times18.5\times18.0$	B32022A3823M***	_	2200	1200

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - M =±20%
 - $K = \pm 10\%$

- *** = Packaging code:
 - 289 = Straight terminals, Ammo pack
 - 189 = Straight terminals, Reel
 - 003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)
 - 000 = Straight terminals, untaped (lead length 6 -1 mm)



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Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Ammo	Reel	Untaped
		$w \times h \times l$	(composition see	pack		
mm	μF	F mm below)		pcs./MOQ	pcs./MOQ	pcs./MOQ
22.5	0.047	$6.0\times15.0\times26.5$	B32023A3473+***	2720	2800	2880
	0.056	$6.0\times15.0\times26.5$	B32023A3563M***	2720	2800	2880
	0.068	$7.0\times16.0\times26.5$	B32023A3683+***	2320	2400	2520
	0.068	$7.5 \times 14.5 \times 26.5$	B32023B3683M***	2200	2000	2280
	0.082	$8.5 \times 16.5 \times 26.5$	B32023A3823+***	1920	2000	2040
	0.10	8.5 imes 16.5 imes 26.5	B32023A3104M***	1920	2000	2040
	0.10	$10.5\times16.5\times26.5$	B32023B3104+***	1560	1600	2160
	0.15	$10.5\times18.5\times26.5$	B32023A3154M***	1560	1600	2160
	0.15	$10.5\times20.5\times26.5$	B32023B3154+***	_	_	2160
	0.22	$12.0\times22.0\times26.5$	B32023A3224M***	_	_	1800
	0.22	$14.5\times29.5\times26.5$	B32023B3224+***	_	_	1040
	0.33	$14.5\times29.5\times26.5$	B32023A3334+***	_	_	1040
	0.39	$14.5\times29.5\times26.5$	B32023A3394M***	_	_	1040
27.5	0.15	$11.0 \times 19.0 \times 31.5$	B32024A3154+***	_	1400	1280
	0.22	$11.0\times19.0\times31.5$	B32024A3224M***	_	1400	1280
	0.22	$11.0 \times 21.0 \times 31.5$	B32024B3224+***	_	1400	1280
	0.33	$13.5\times23.0\times31.5$	B32024A3334M***	—	1000	1040
	0.33	$14.0\times24.5\times31.5$	B32024B3334+***	—	_	1040
	0.47	$15.0\times24.5\times31.5$	B32024A3474M***	—	_	960
	0.47	$16.0\times32.0\times31.5$	B32024C3474+***	_	—	880

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

- + = Capacitance tolerance code:
 - M =±20%
 - K = ±10%

*** = Packaging code:

- 289 = Straight terminals, Ammo pack
- 189 = Straight terminals, Reel
- 003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)
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Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Ammo	Reel	Untaped
		$w \times h \times l$	(composition see	pack		
mm	μF	mm	below)	pcs./MOQ	pcs./MOQ	pcs./MOQ
27.5	0.47	$18.0\times27.5\times31.5$	B32024B3474+***	_	_	800
	0.56	$16.0\times32.0\times31.5$	B32024A3564+***	-	—	880
	0.68	$18.0\times33.0\times31.5$	B32024B3684+***	—	—	800
	0.68	$19.0\times30.0\times31.5$	B32024A3684M***	_	_	720
	0.68	$21.0\times31.0\times31.5$	B32024C3684+***	_	_	720
	0.82	$22.0\times36.5\times31.5$	B32024A3824+***	_	_	640
	1.0	$22.0\times36.5\times31.5$	B32024A3105M***	_	_	640
37.5	0.33	$12.0\times22.0\times41.5$	B32026A3334+***	_	_	1620
	0.47	$14.0\times25.0\times41.5$	B32026A3474+***	-	—	1380
	0.56	$14.0\times25.0\times41.5$	B32026A3564M***	—	—	1380
	0.56	$16.0\times28.5\times41.5$	B32026B3564+***	_	_	800
	0.68	$16.0\times28.5\times41.5$	B32026A3684+***	_	_	800
	0.82	$16.0 \times 28.5 \times 41.5$	B32026A3824M***	—	_	800
	0.82	$18.0\times32.5\times41.5$	B32026B3824+***	—	_	720
	1.0	$18.0\times32.5\times41.5$	B32026A3105M***	_	_	720
	1.0	$20.0\times39.5\times42.0$	B32026B3105+***	—	—	640

MOQ = Minimum Order Quantity, consisting of 4 packing units. Further intermediate capacitance values on request.

Composition of ordering code

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 - K = ±10%

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Technical data

Reference standard: IEC 60384-14:2013/AMD1:2016. All data given at T = 20 $^{\circ}$ C, unless otherwise specified.

Rated AC voltage (IEC 60384-14:2013)	300 V (50/60 Hz)
Maximum continuous DC voltage V _{DC}	1500 V at $T_{op} \le 85 \ ^{\circ}C$
C	1.5% / °C derating when 85 °C < T_{op} \leq 110 °C
Maximum continuous AC voltage V _{AC}	
at $T_{op} \le 85 \ ^{\circ}C$	480 V (50/60 Hz)
Max. operating temperature T _{op,max}	+110 °C
DC test voltage	4000 V (C \leq 0.33 μ F), 3700 V (C > 0.33 μ F), 2 s

The repetition of this DC voltage test may damage the capacitor. Special care must be taken in case of use several capacitors in a parallel configuration.

Dissipation factor tan δ (in 10 ⁻³)		$C_{\text{R}} \leq 0.33 \; \mu F$	C _R > 0.33 μF
at 20 °C (upper limit values)	at 1 kHz	1	1
Insulation resistance R _{ins} or time constant	$C_{R} \leq 0.33 \ \mu F$:	C _R > 0.33 μF
$\tau = C_R \cdot R_{ins}$ at 100 V DC, 20 °C,	100 000 MΩ		30 000 s
rel. humidity \leq 65% and for 60 s			
(minimum as-delivered values)			
Passive flammability category	В		
Capacitance tolerances (measured at 1 kHz)	±10% (K), ±2	20% (M)	

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

" k_0 " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V²/µs.

Note:

The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and k₀ values

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
dV/dt in V/µs	800	600	500	400	300
k₀in V²/µs	677 000	508 000	423 000	338 000	254 000



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Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Electrical	IEC	Voltage Proof:		Within specified limits
parameters	60384-14:2013/	Between terminals,		
	AMD1:2016	1500 V AC, 1 min.		
		Terminals and encl	osure:	
		2 V _R + 1500 V AC		
		Insulation resistanc	e, R _{ins}	
		Capacitance, C		
		Dissipation factor, t	an δ	
Robustness	IEC	Tensile strength (te	st Ua1)	Capacitance and tan δ
of termina-	60068-2-21:2006	Wire diameter	Tensile	within specified limits
tions			force	
		0.5 < d₁ ≤ 0.8 mm	10 N	
		$0.8 < d_1 \le 1.25 \text{ mm}$	-	
Resistance	IEC	Solder bath temper		$\Delta C/C_0 \leq 5\%$
to soldering	60068-2-20:2008,	260 ±5 °C, immersi		tan δ within specified limits
heat	test Tb,	10 seconds		tan o within specified limits
neat	method 1A			
Rapid	IEC	$T_A = $ lower category	temperature	No visible damage
change of	60384-14:2013/	$T_{\rm B}$ = upper category		$ \Delta C/C_0 \le 5\%$
temperature		Five cycles, duratio	•	tan δ within specified limits
		•		
Vibration	IEC	Test F _c : vibration si		No visible damage
	60384-14:2013/	Displacement: 0.75		
	AMD1:2016	Accleration: 98 m/s		
		Frequency: 10 Hz.		
		Test duration: 3 ort	nogonal axes,	
		2 hours each axe		
Bump	IEC	Test Eb: Total 400		No visible damage
	60384-14:2013/	400 m/s ² mounted of	on PCB	$ \Delta C/C_0 \le 5\%$
	AMD1:2016	6 ms duration		tan δ within specified limits
Climatic	IEC	Dry heat Tb / 16 h		No visible damage
sequence	60384-14:2013/	Damp heat cyclic, 1	-	$ \Delta C/C_0 \le 5\%$
	AMD1:2016	+55 °C / 24 h / 95%	5 100% RH	$ \Delta \tan \delta \le 0.008$ for C $\le 1 \mu F$
		Cold Ta / 2 h		$ \Delta \tan \delta \le 0.005$ for C > 1 μ F
		Damp heat cyclic, 5		Voltage proof
		+55 °C / 24 h / 95%	100% RH	$R_{ins} \ge 50\%$ of initial limit



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Test	Reference	Conditions of test	Performance requirements
Damp heat, steady state	IEC 60384-14:2013/ AMD1:2016	Test Ca 40 °C / 93% RH / 56 days	$\begin{array}{l} \text{No visible damage} \\ \Delta C/C_0 \leq 5\% \\ \Delta \ tan \ \delta \leq 0.008 \ \text{for } C \leq 1 \ \mu\text{F} \\ \Delta \ tan \ \delta \leq 0.005 \ \text{for } C > 1 \ \mu\text{F} \\ \text{Voltage proof} \\ R_{\text{ins}} \geq 50\% \ \text{of initial limit} \end{array}$
Impulse test Endurance	IEC 60384-14:2013/ AMD1:2016	3 impulses Tb / 1.7 V _R / 1000 hours, 1000 V _{RMS} for 0.1 s every hour	$\begin{array}{l} \text{No visible damage} \\ \Delta C/C_0 \leq 10\% \\ \Delta \ tan \ \delta \leq 0.008 \ \text{for } C \leq 1 \ \mu\text{F} \\ \Delta \ tan \ \delta \leq 0.005 \ \text{for } C > 1 \ \mu\text{F} \\ \text{Voltage proof} \\ \textbf{R}_{\text{ins}} \geq 50\% \ \text{of initial limit} \end{array}$
Passive flammability	IEC 60384-14:2013/ AMD1:2016	Flame applied for a period of time depending on capacitor volume	В
Active flammability	IEC 60384-14:2013/ AMD1:2016	20 discharges at 2.5 kV + V _R	The cheesecloth shall not burn with a flame



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Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20:2008, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2:2007, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

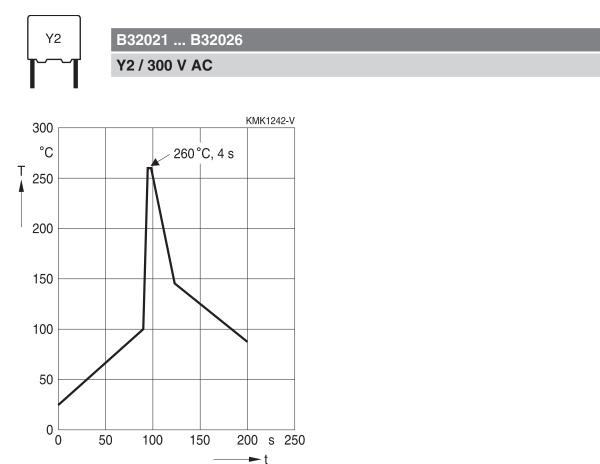
Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 + 0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20:2008, test Tb, method 1. Conditions:

Serie	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	(lead spacing >7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)	-	5±1 s
MKP MKT	(lead spacing ≤7.5 mm) uncoated (lead spacing ≤10 mm) insulated (B32559)		<4 s recommended soldering profile for MKT uncoated (lead spacing \leq 10 mm) and insulated (B32559)





Immersion depth	2.0 +0/ -0.5 mm from capacitor body or seating plane	
Shield	Heat-absorbing board, (1.5 \pm 0.5) mm thick, between capacitor body and liquid solder	
Evaluation criteria:		
Visual inspection	No visible damage	
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors	
tan δ	As specified in sectional specification	

1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

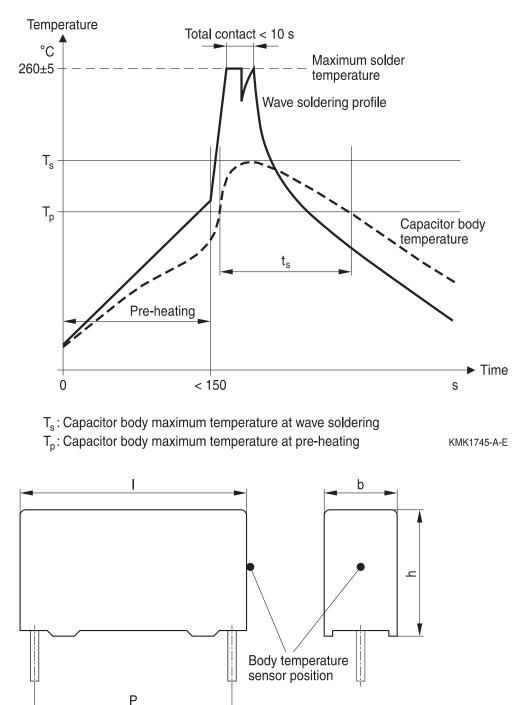




The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

Recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



KMK1744-9-E





Body temperature should follow the description below:

- MKP capacitor During pre-heating: T_p ≤110 °C During soldering: T_s ≤120 °C, t_s ≤45 s
- MKT capacitor During pre-heating: T_p ≤125 °C During soldering: T_s ≤160 °C, t_s ≤45 s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be \leq 120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings \leq 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to our Film Capacitors Data Book in case more details are needed.

Application note

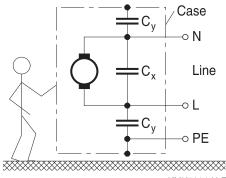
A Y capacitor to be connected between AC lines and the Frame Ground (FG) has an effect of emitting common mode current to the FG.Leak current corresponding in frequency and voltage to the AC power supply flows in the Y capacitor.

As the capacity of a Y capacitor grows, leak current also increases. This can cause electric shock. Therefore, UL and other safety standards restrict the capacity so that the amount of leak current does not exceed a certain level. Usually, two Y capacitors are used, as shown in Figure below. As AC lines are connected with capacitors, they are effective in reducing differential mode noises. In particular, they are effective for high frequency ranges of 8 to 10 MHz.

Example of EMI suppression, typical application:







KMK0804-U-E





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Y2 / 300 V AC

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of TDK Electronics.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Торіс	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6:2007. TDK Electronics offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





Торіс	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Design of our capacitors

Our EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC 60384-14:2013 (4th edition) / UL 60384-14:2014 (2nd edition) establishes high voltage tests performed at $4.3 \times V_R - 1$ minute, impulse testing at 2500 V for C = 1 µF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.





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Y2 / 300 V AC

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the order-ing codes are due to different processes employed and do not affect the specifications of the respective products.

Detailed information can be found on the Internet under

www.tdk-electronics.tdk.com/orderingcodes.

Correlation of data sheet values and modelling tool outputs

Data sheet values and results of design tools may deviate as they have not been derived in the same context.

While data sheets show individual parameter statements without considering a possible dependency to other parameters. Tools model a complete given scenario as input and processed inside the tool.

Furthermore as we constantly strive to improve our models, the results of tools can change over time and be a non-binding indication only.



Y2

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_{c}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
β _c	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C _R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
∆t	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V / \Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f ₂	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F _D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F _τ	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)



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Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
İ _z	Capacitance drift	Inkonstanz der Kapazität
k _o	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λο	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P _{diss}	Dissipated power	Abgegebene Verlustleistung
P _{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R _i	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R _₽	Parallel resistance	Parallelwiderstand
R _s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$\tan \delta_{D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ _P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
an δ _s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T _{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{oL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T _{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer



Y2

Symbol	English	German
V _{AC}	AC voltage	Wechselspannung
V _c	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
Vi	Input voltage	Eingangsspannung
Vo	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V _p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V _R	Rated voltage	Nennspannung
ν _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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Release 2020-06